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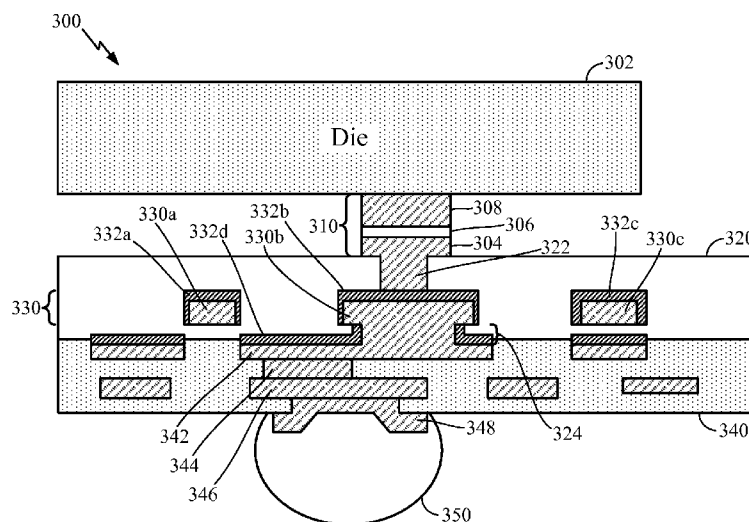
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- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii))

[Continued on next page]

(54) Title: HIGH DENSITY FAN OUT PACKAGE STRUCTURE

**FIG. 3**

(57) **Abstract:** A high density fan out package structure may include a contact layer. The contact layer includes a conductive interconnect layer having a first surface facing an active die and a second surface facing a redistribution layer. The high density fan out package structure has a barrier layer on the first surface of the conductive interconnect layer. The high density fan out package structure may also include the redistribution layer, which has conductive routing layers. The conductive routing layers may be configured to couple a first conductive interconnect to the conductive interconnect layer. The high density fan out package structure may further include a first via coupled to the barrier liner and configured to couple with a second conductive interconnect to the active die.



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